



Semiconductor Device Type: T2C TO-247-1.622x0.625x0.197in-MatteTin						Package Homogeneous Materials				
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	8.60	(mg) Total	Die	% of Total Weight	0.14
Silicon carbide	409-21-2	Die	0.14	8.60	1448		Silicon carbide	409-21-2	100.00	
Copper	7440-50-8	Leadframe	63.56	3774.81	635649		Total		100.00	
Iron	7439-89-6	Leadframe	0.05	2.84	478					
Nickel	7440-02-0	Leadframe	0.06	3.59	605	3782.00	(mg) Total	Leadframe	% of Total Weight	63.69
Phosphorus	7723-14-0	Leadframe	0.01	0.76	128		Copper	7440-50-8	99.81	
Lead	7439-92-1	Die Attach Material	0.11	6.40	1078		Iron	7439-89-6	0.08	
Silver	7440-22-4	Die Attach Material	0.00	0.17	29		Nickel	7440-02-0	0.09	
Tin	7440-31-5	Die Attach Material	0.00	0.13	22		Phosphorus	7723-14-0	0.02	
Aluminum	7429-90-5	Wire	0.02	1.30	219		Total		100.00	
Silicon dioxide	7631-86-9	Mold Compound	23.72	1408.60	237198					
Benzophenone-3,3',4,4'-tetracarboxylic dianhydride	2421-28-5	Mold Compound	3.30	196.21	33040	6.70	(mg) Total	Die Attach Material	% of Total Weight	0.11
Quartz	14808-60-7	Mold Compound	3.13	185.89	31302		Lead	7439-92-1	95.52	
Carbon Black	1333-86-4	Mold Compound	0.31	18.59	3130		Silver	7440-22-4	2.54	
4,4'-carbonyldipthalic acid	2479-49-4	Mold Compound	0.31	18.59	3130		Tin	7440-31-5	1.94	
Antimony trioxide	1309-64-4	Mold Compound	3.13	185.89	31302		Total		100.00	
2,2',6,6'-tetrabromo-4,4'-isopropylidenediphenol	40039-93-8	Mold Compound	0.87	51.64	8696					
Tin	7440-31-5	Lead Finish	1.25	74.50	12545	1.30	(mg) Total	Wire	% of Total Weight	0.02
TOTALS:			100.00	5938.51	1,000,000		Aluminum	7429-90-5	100.00	
5938.51 mg Total Mass							Total		100.00	
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						2065.41	(mg) Total	Mold Compound	% of Total Weight	34.78
							Silicon dioxide	7631-86-9	68.20	
							Benzophenone-3,3',4,4'-tetracarboxylic dianhydride	2421-28-5	9.50	
							Quartz	14808-60-7	9.00	
							Carbon Black	1333-86-4	0.90	
							4,4'-carbonyldipthalic acid	2479-49-4	0.90	
							Antimony trioxide	1309-64-4	9.00	
							2,2',6,6'-tetrabromo-4,4'-isopropylidenediphenol	40039-93-8	2.50	
							Total		100.00	
						74.50	(mg) Total	Lead Finish	% of Total Weight	1.25
							Tin	7440-31-5	100.00	
						5938.51	Total		100.00	100.00